FAIRCHILD
SEMICONDUCTOR®

May 2009

FST3257
Quad 2:1 Multiplexer / Demultiplexer Bus Switch

Features

- 4Ω Switch Connection Between Two Ports
- Minimal Propagation Delay Through the Switch
- Low I_{CC}
- Zero Bounce in Flow-Through Node
- Control Inputs Compatible with TTL Level

Description

The Fairchild Switch FST3257 is a quad 2:1 high-speed CMOS TTL-compatible multiplexer / demultiplexer bus switch. The low on resistance of the switch allows inputs to be connected to outputs without adding propagation delay or generating additional ground bounce noise.

When /OE is LOW, the select pin connects the A port to the selected B port output. When /OE is HIGH, the switch is OPEN and a high-impedance state exists between the two ports.

Ordering Information

Part Number	Operating Temperature Range	Eco Status	Package	Packing Method
FST3257M	-40 to 85°C	RoHS	16-Lead Small Outline Integrated Circuit (SOIC) JEDEC MS-012,0.150 Narrow	Tubes
FST3257MX	-40 to 85°C			Tape and Reel
FST3257QSC	-40 to 85°C	Green	16-Lead Quarter Size Outline Package (QSOP) JEDEC MO-137 0.150 Inch Wide	Tubes
FST3257QSCX	-40 to 85°C			Tape and Reel
FST3257MTC	-40 to 85°C	RoHS	16-Lead Thin Shrink Small Outline Package (TSSOP) JEDEC MO-153, 4mm Wide	Tubes
FST3257MTCX	-40 to 85°C			Tape and Reel

For Fairchild's definition of Eco Status, please visit: http://www.fairchildsemi.com/company/green/rohs_green.html.
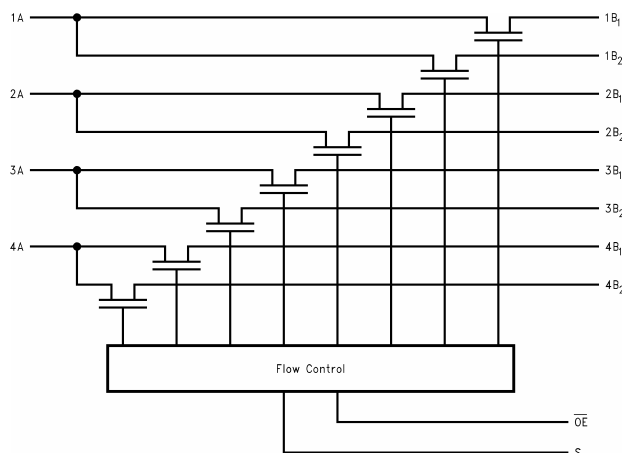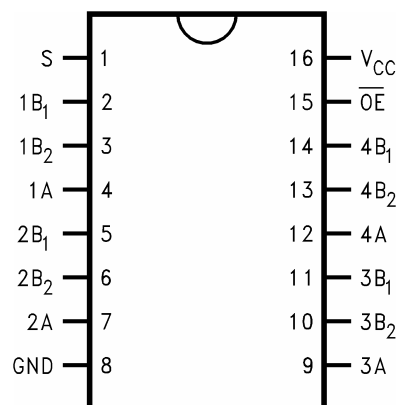
Pin Assignments

Figure 1. Logic Diagram

Figure 2. Connection Diagram

Pin Descriptions

Pin #	Names	Description
1	S	Select Input
2, 3, 5, 6, 10, 11, 13, 14	$1B_1$, $1B_2$, $2B_1$, $2B_2$, $3B_1$, $3B_2$, $4B_1$, $4B_2$	Bus B
4, 7, 9, 12	1A, 2A, 3A, 4A	Bus A
8	GND	Ground
15	/OE	Bus Switch Enables
16	VCC	Supply Voltage

Truth Table

Select Inputs	Bus Switch Enabled	Function
S	Logic Level HIGH	Disconnected
Logic Level LOW	Logic Level LOW	$A=B_1$
Logic Level HIGH	Logic Level LOW	$A=B_2$

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Min.	Max.	Unit
V_{CC}	Supply Voltage	-0.5	+7.0	V
V_S	DC Switch Voltage	-0.5	+7.0	V
V_{IN}	DC Input Voltage[1]	-0.5	+7.0	V
I_{IK}	DC Input Current		-50	mA
I_{OUT}	DC Output Sink Current		128	mA
I_{CC}/I_{GND}	DC V_{CC}/GND Current		±100	mA
T_{STG}	Storage Temperature Range	-65	+150	°C

Note:
1. The input and output negative voltage ratings may be exceeded if the input and output diode current ratings are observed.

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parameter		Min.	Max.	Unit
V_{CC}	Power Supply Operating		3.0	5.5	V
V_{IN}	Input Voltage		0	5.5	V
V_{OUT}	Output Voltage		0	5.5	V
t_r, t_f	Input Rise and Fall Time	Switch Control Input	0	5	ns/V
		Switch I/O	0	DC	
T_A	Free Air Operating Temperature		-40	+85	°C

Note:
2. Unused control inputs must be held HIGH or LOW. They may not float.

DC Electrical Characteristics

Symbol	Parameter	Conditions	V$_{CC}$ (V)	T$_A$=-40 to +85°C			Units
				Min.	Typ.[3]	Max.	
V$_{IK}$	Clamp Diode Voltage	I$_{IN}$=-18mA	4.5			-1.2	V
V$_{IH}$	High-Level Input Voltage		3.0 to 3.6[5]	1.8			V
			4.0 to 5.5	2.0			
V$_{IL}$	Low-Level Input Voltage		3.0 to 3.6[5]			0.7	V
			4.0 to 5.5			0.8	
I$_{IN}$	Input Leakage Current	$0 \leq V_{IN} \leq 5.5$	5.5			±1.0	µA
I$_{OZ}$	Off-state Leakage Current	$0 \leq A, B \leq V_{CC}$	5.5			±1.0	µA
R$_{ON}$	Switch On Resistance[4]	V$_{IN}$=0V, I$_{IN}$=64mA	3.3[5]		13	20	Ω
		V$_{IN}$=0V, I$_{IN}$=30mA	3.3[5]		28	40	
		V$_{IN}$=2.4V, I$_{IN}$=15mA	3.3[5]		200	230	
		V$_{IN}$=2.4V, I$_{IN}$=15mA	3.0[5]		210	250	
		V$_{IN}$=0V, I$_{IN}$=64mA	4.5		4	7	
		V$_{IN}$=0V, I$_{IN}$=30mA	4.5		4	7	
		V$_{IN}$=2.4V, I$_{IN}$=15mA	4.5		8	15	
		V$_{IN}$=2.4V, I$_{IN}$=15mA	4.0		11	20	
I$_{CC}$	Quiescent Supply Current	V$_{IN}$=V$_{CC}$ or GND, I$_{OUT}$=0,	5.5			3	µA
∆I$_{CC}$	Increase in I$_{CC}$ per input	One Input at 3.4V, Other inputs at V$_{CC}$ or GND	5.5			2.5	mA

Notes:
3. Typical values are at nominal V$_{CC}$ for the V$_{CC}$ range and T$_A$=25°C.
4. Measured by the voltage drop between A and B pins at the indicated current through the switch. On resistance is determined by the lower of the voltages on the A or B pins.
5. This parameter is guaranteed by design, but is not tested.

AC Electrical Characteristics

| Symbol	Parameter	Conditions	TA=-40 to +85°C, CL= 50pF, RU=RD=500Ω						Units	Figure
			Vcc= 4.5 to 5.5V		Vcc=4.0V		Vcc=3.0 to 3.6V(7)			
			Min.	Max.	Min.	Max.	Min.	Max.		
t_{PHL}, t_{PLH}	Propagation Delay Bus to Bus(6)	V_{IN}=Open		0.25		0.25		0.25	ns	Figure 3 Figure 4
	Propagation Delay Select to Bus A(6)						1.0	6.8		
t_{PZH}, t_{PZL}	Output Enable Time, Select to Bus B	V_{IN}=7V for t_{PZL} V_{IN}=Open for t_{PZH}	1.0	5.0		5.5	1.0	7.9	ns	Figure 3 Figure 4
	Output Enable Time, Select to Bus /OE						1.0	8.5		
t_{PHZ}, t_{PLZ}	Output Disable Time, Select to Bus B	V_{IN}=7V for t_{PLZ} V_{IN}=Open for t_{PHZ}	1.5	5.3		5.6	1.0	9.9	ns	Figure 3 Figure 4
	Output Disable Time, Select to Bus /OE						1.5	9.9		

Notes:
6. This parameter is guaranteed by design but is not tested. The bus switch contributes no propagation delay other than the RC delay of the typical on resistance of the switch and the 50pF load capacitance, when driven by an ideal voltage source (zero output impedance).
7. These parameters are guaranteed by design, but not tested.
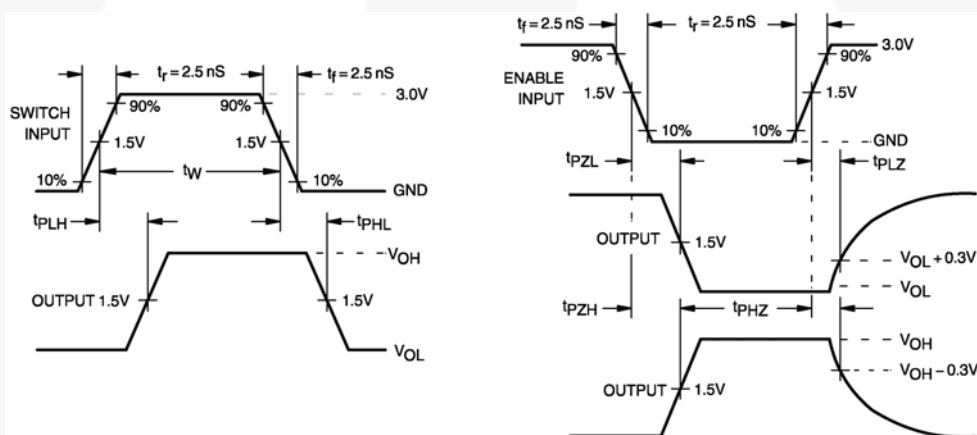
Capacitance

T_A=+25°C, f=1MHz. Capacitance is characterized by not tested.

Symbol	Parameter		Conditions	Typ.	Max.	Units
C_{IN}	Control Pin Input Capacitance		V_{CC}=5.0V	3.0		pF
$C_{I/O}$	Input/Output Capacitance	A Port	V_{CC} /OE=5.0V	7.0		pF
		B Port		5.0		
		A Port	V_{CC} /OE=3.3V	3.0		pF
		B Port		3.5		

AC Loadings and Waveforms
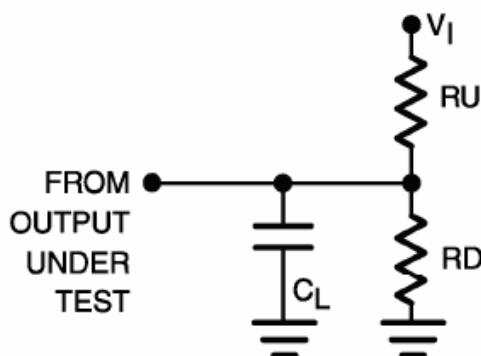
Notes:
8. Input driven by 50Ω source terminated in 50Ω.
9. C_L included load and stray capacitance.
10. Input PRR=1.0MHz, tw=500ns.

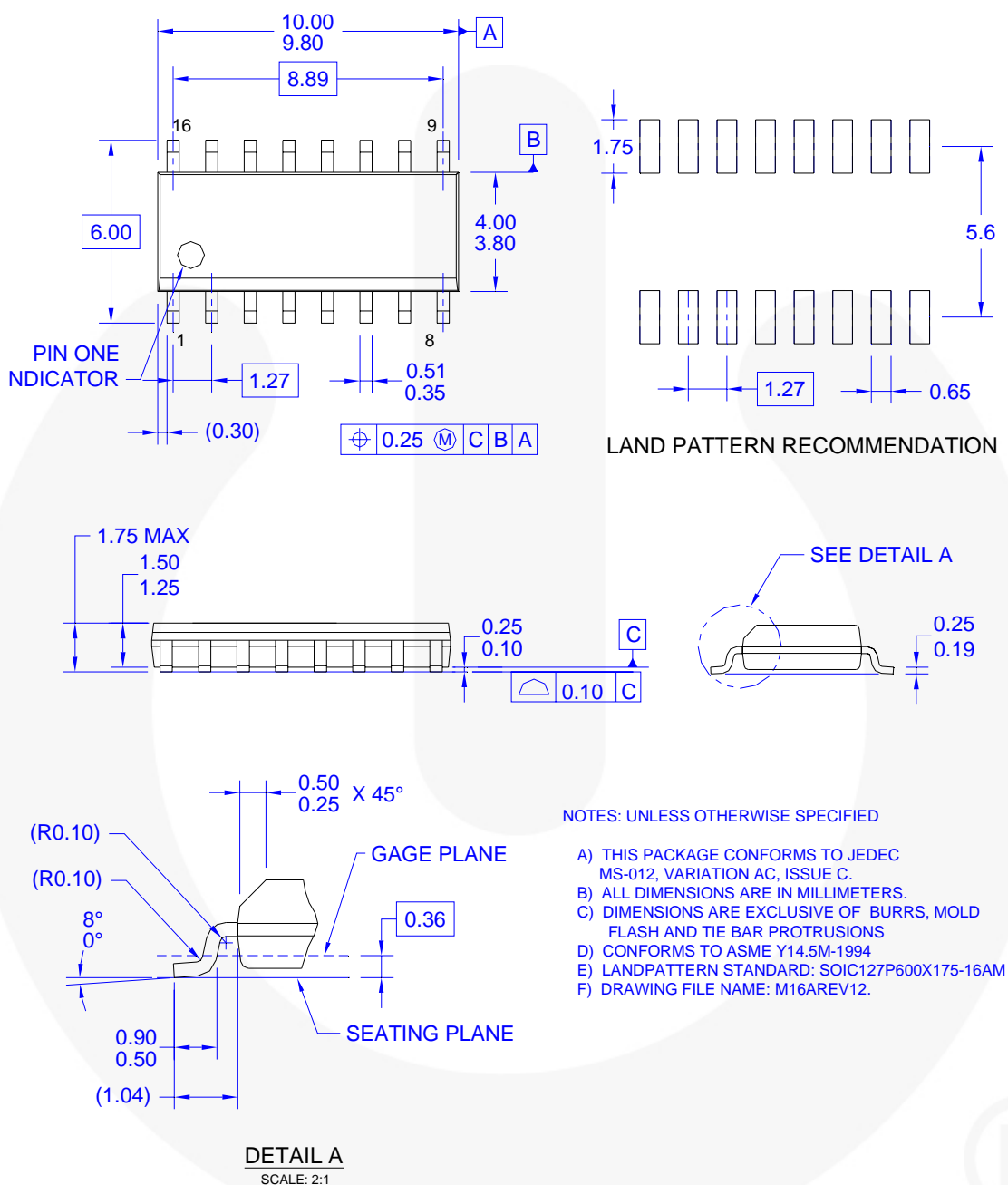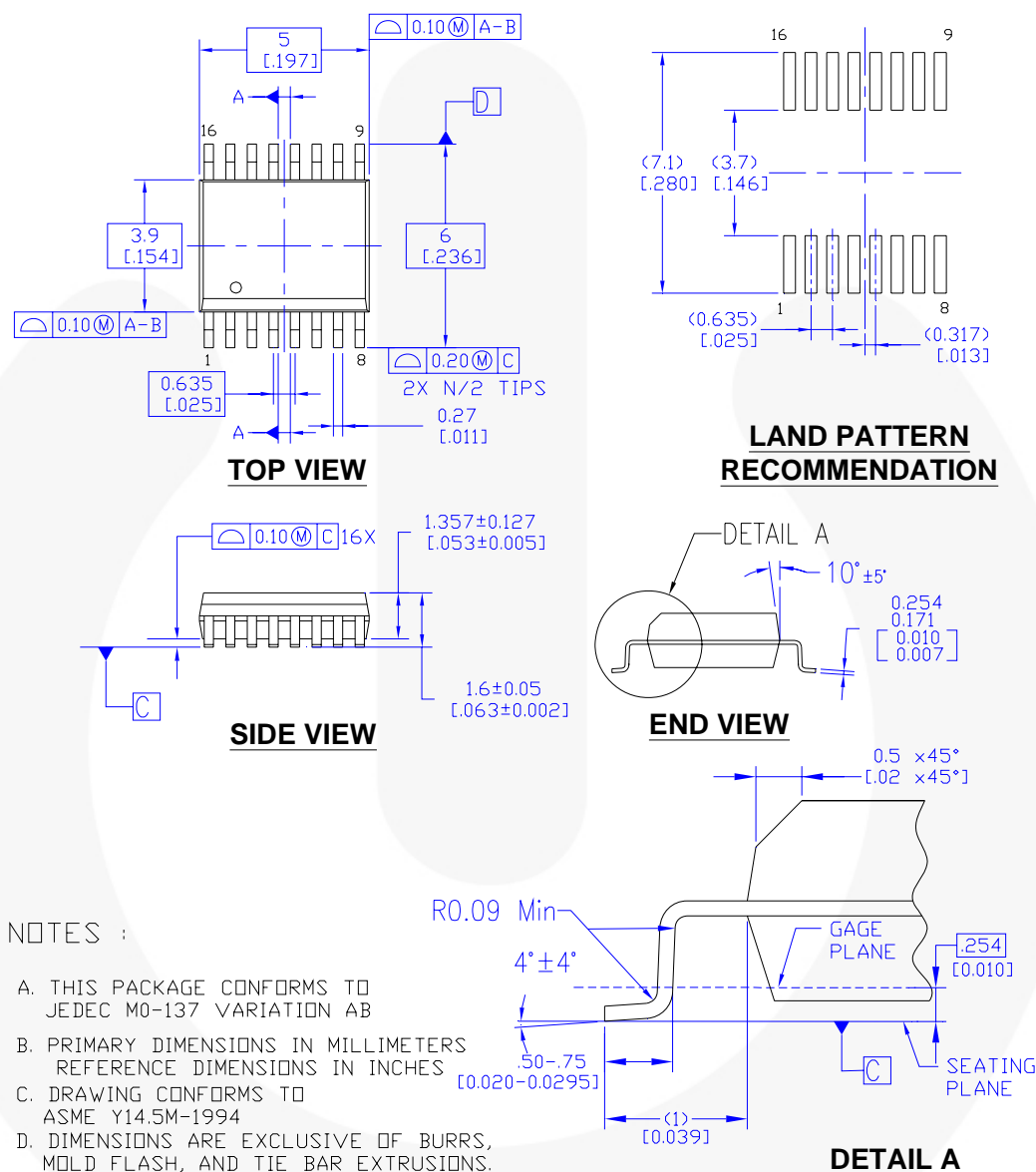**Figure 3. AC Test Circuit**

Figure 4. AC Waveforms

www.fairchildsemi.com

Physical Dimensions

10.00 / 9.80 — A

8.89

16 9

B

1.75

6.00

4.00 / 3.80

5.6

PIN ONE INDICATOR

1 8

1.27

0.51 / 0.35

(0.30)

⊕ | 0.25 Ⓜ | C | B | A

1.27

0.65

LAND PATTERN RECOMMENDATION

1.75 MAX
1.50
1.25

0.25 / 0.10

C

⌒ | 0.10 | C

SEE DETAIL A

0.25 / 0.19

0.50 / 0.25 X 45°

(R0.10)

(R0.10)

GAGE PLANE

0.36

8° / 0°

SEATING PLANE

0.90 / 0.50

(1.04)

NOTES: UNLESS OTHERWISE SPECIFIED

A) THIS PACKAGE CONFORMS TO JEDEC
   MS-012, VARIATION AC, ISSUE C.
B) ALL DIMENSIONS ARE IN MILLIMETERS.
C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD
   FLASH AND TIE BAR PROTRUSIONS
D) CONFORMS TO ASME Y14.5M-1994
E) LANDPATTERN STANDARD: SOIC127P600X175-16AM
F) DRAWING FILE NAME: M16AREV12.

DETAIL A
SCALE: 2:1

Figure 5.   16-Lead Small Outline Integrated Circuit (SOIC) JEDEC MS-012,0.150 Narrow

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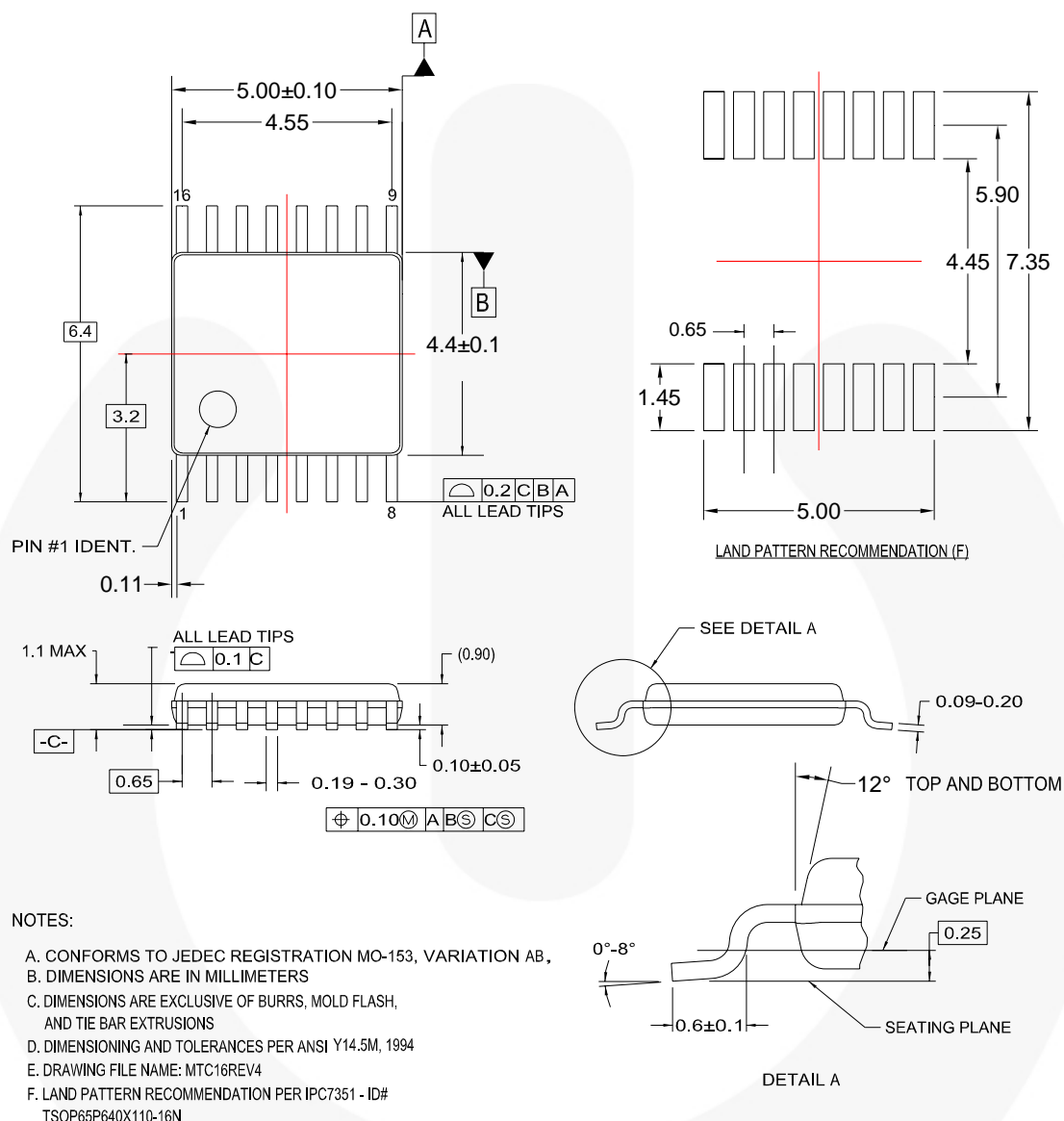*http://www.fairchildsemi.com/packaging/.*

Physical Dimensions

TOP VIEW

LAND PATTERN RECOMMENDATION

SIDE VIEW

END VIEW

DETAIL A

NOTES :

A. THIS PACKAGE CONFORMS TO JEDEC MO-137 VARIATION AB

B. PRIMARY DIMENSIONS IN MILLIMETERS REFERENCE DIMENSIONS IN INCHES

C. DRAWING CONFORMS TO ASME Y14.5M-1994

D. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

MQA16AREVB

Figure 6. 16-Lead Quarter Size Outline Package (QSOP) JEDEC MO-137 0.150 Inch Wide

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Physical Dimensions

A
5.00±0.10
4.55
16
9
6.4
4.4±0.1
B
3.2
1
8
□ 0.2 C B A
ALL LEAD TIPS
PIN #1 IDENT.
0.11

5.90
4.45 7.35
0.65
1.45
5.00
LAND PATTERN RECOMMENDATION (F)

1.1 MAX
ALL LEAD TIPS
□ 0.1 C
(0.90)
-C-
0.10±0.05
0.65
0.19 - 0.30
⊕ 0.10Ⓜ A BⓈ CⓈ

SEE DETAIL A
0.09-0.20
12° TOP AND BOTTOM
GAGE PLANE
0°-8°
0.25
0.6±0.1
SEATING PLANE
DETAIL A

NOTES:

A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AB,
B. DIMENSIONS ARE IN MILLIMETERS
C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS
D. DIMENSIONING AND TOLERANCES PER ANSI Y14.5M, 1994
E. DRAWING FILE NAME: MTC16REV4
F. LAND PATTERN RECOMMENDATION PER IPC7351 - ID# TSOP65P640X110-16N

MTC16rev4

Figure 7.   16-Lead Thin Shrink Small Outline Package (TSSOP) MO-153, 4.4mm Wide

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No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
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